



2814

#10 / Supp.  
IDS  
11-6-01  
R. Stokes

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of )  
Shinji TAKEDA et al. ) Atty. Docket No.: **TM&K0008**  
Serial No. 09/785,486 )  
Filed: February 20, 2001 ) Group Art Unit: 2814  
For: SEMICONDUCTOR DEVICE AND )  
PROCESS FOR FABRICATION ) Examiner:  
THEREOF )

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**SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT**

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

This is a Supplemental Information Disclosure Statement with regard to the above-identified application. Copies of the documents listed in the attached Forms PTO/SB/08A&B are attached.

Document A relates to an adherent insulating tape and a semiconductor device that utilizes such a tape. Document B relates to a heat-resistant adhesive material. Document C relates to a film adhesive containing a polyimide resin. Document D also relates to a film adhesive containing a polyimide resin. Document E relates to a polyimide and a heat-resistant adhesive made from a polyimide. Document F relates to a film adhesive with high thermal conductivity that is bondable by hot melt bonding. Document G relates to a method for producing a double-layered adhesive sheet. Document H relates to an electrically conductive

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adhesive sheet. Document I relates to an adhesive film, its production, and method for adhesion. Document J relates to a die bonding material. Document K relates to a manufacturing method of a die bonding semiconductor device. Document L relates to a semiconductor device and its manufacture. Document M also relates to a semiconductor device and its manufacture. Document N relates to a resin system adhesive agent for insulating die bonding. Document O relates to a filmy adhesive and its production. Document P relates to a semiconductor device and its manufacturing method. Document Q relates to a resin sealed semiconductor device. Document R relates to a resin composition with improved physical properties at a high temperature. Document S relates to a semiconductor device and its manufacturing method. Document T relates to a three-layer polyimidesiloxane adhesive tape. Document U relates to new type film-adhesives for microelectronics application. Document V relates to properties of major thermosetting and thermoplastic resins. Document W relates to a die bonding adhesive film.

It is hereby certified that no item of information contained in this information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application, and, to the knowledge of the undersigned after making reasonable inquiry, no item of information contained in this information disclosure statement was known to any individual designated in 37 C.F.R. §1.56(c) more than three months prior to the filing of this information disclosure statement.

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It is respectfully requested that the attached documents be considered and officially cited, and that a copy of the Forms PTO/SB/08A&B, initialed by the Examiner to indicate that the documents have been considered, be returned to the applicants.

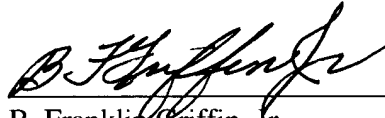
Since no Office Action has issued in this case, it is believed that no fee is required. However, if it is determined that a fee is required, authorization is hereby given to deduct said fee from the undersigned's Deposit Account No. 50-1281.

Respectfully submitted,

GRIFFIN & SZIPL, P.C.

11-01-01

Date



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